

RO4000[®] LoPro[®] Laminate

Quick Reference Processing Guide

Material Description:	Reverse-treated copper clad, glass reinforced, ceramic filled hydrocarbon resin composite material
Storage:	Ambient
INNER LAYER PREPARATION	
Tooling:	Compatible with most round and slotted pinning systems
Surface Preparation for Photoresist Applications:	Process as is or use chemical or mechanical preparation depending upon core thickness
Photoresist Applications:	Standard film and liquid resists & procedures
DES Processing:	Standard processing. Thin cores may require leaders
Oxide Treatment:	Use procedures associated with oxide or oxide alternative of choice
BONDING	
Final Preparation:	125°C to 150°C (257°F - 302°F) Pre-bake recommended
Multilayer Adhesive System:	Compatible with RO4400™ materials and most thermoset prepregs
Multilayer Bond Cycle:	Use bond parameters associated with adhesive system.
PTH AND OUTER LAYER/DOUBLE SIDED CIRCUIT PROCESSING	
Drilling:	Standard entry/exit materials such as sheeted aluminum and pressed phenolic. Use new drills. Controlled infeeds, speeds, and retract rates. Inspect holes to determine tool life
Deburring:	Mechanical debur/scrub acceptable for thicker cores/builds
Hole Preparation:	Chemical or plasma desmear may be required. Etchback is not recommended.
Metallization:	Electroless copper or direct deposit processes.
PTH PLATING AND OUTER LAYER IMAGING	
Final Surfaces:	Compatible with most final metals surfaces and OSP's. Preserve post-etch surface and bake cores prior to application of LPI.
Final Circuitization:	RO4000 [®] LoPro [®] laminates can be routed, punched, or V-scored. Diamond-cut or multi-fluted chipbreaker router bits are recommended. V-score depth should be <math>< \frac{1}{2}</math> of the material thickness or less. Deeper cuts could result in pre-mature breakaway.

Prolonged exposure in an oxidative environment may cause changes to the dielectric properties of hydrocarbon based materials. The rate of change increases at higher temperatures and is highly dependent on the circuit design. Although Rogers' high frequency materials have been used successfully in innumerable applications and reports of oxidation resulting in performance problems are extremely rare, Rogers recommends that the customer evaluate each material and design combination to determine fitness for use over the entire life of the end product.

The information in this processing guideline is intended to assist you in designing with Rogers' circuit materials. It is not intended to and does not create any warranties express or implied, including any warranty of merchantability or fitness for a particular purpose or that the results shown on this processing guideline will be achieved by a user for a particular purpose. The user should determine the suitability of Rogers' circuit materials for each application.

These commodities, technology and software are exported from the United States in accordance with the Export Administration regulations. Diversion contrary to U.S. law prohibited.

The Rogers' logo RO4400, RO4000 and LoPro are trademarks of Rogers Corporation or one of its subsidiaries.

©2023 Rogers Corporation, Printed in U.S.A. All rights reserved.

Revised 1652 081123 **Publication #92-504**